



Camera Sockets

FEATURES AND SPECIFICATIONS

[查询"47337-0001"供应商](#)

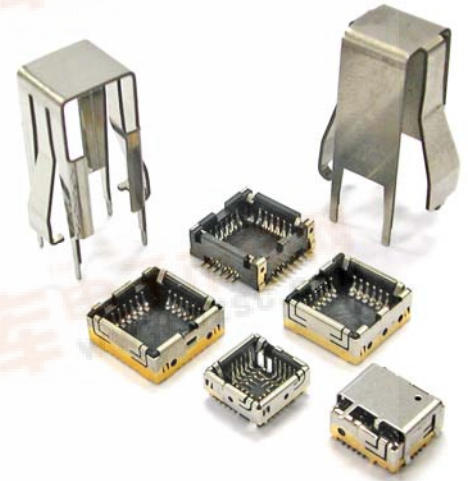
Molex's Mobile Phone Camera Sockets Offer Versatility for Mounting Camera Modules

The mobile phone has become more than just an audio communication device over the past few years. With advances in cellular networks and camera modules, improved bandwidths have provided mobile phone manufacturers more options to include cameras and video-conference capabilities.

Visual transmission is via the camera module connected to the camera socket. The entire assembly is either soldered onto flex or PCB of the mobile phone. These sockets allow mobile phone makers to reduce their bills-of-material (BOM) due to the socket's compact design and simple assembly process. Another major benefit arising from the size of the sockets is the reduction in space.

Molex offers a wide range of socket configurations that includes application extraction tooling to disengage the camera module from the socket.

- 47249** 8 x 8, Top Mount
- 47337** 8.5 x 8.5, Top Mount
- 47356** 6 x 6, Mid Mount with Cap
- 47357** 8 x 8, Mid Mount
- 47578** 6 x 6, Top Mount



Features

Benefits

- | | |
|--|--------------------------------------|
| • Low profile | • Excellent for Slim type cell phone |
| • High reliability | • Stable high quality image |
| • Side contact and bottom contact solution | • Options for module mating design |
| • Top mount and mid mount solution | • Provides various height options |
| • Top cover available for | • EMI and module holding |
| • Module extraction tool available | • Allows re-work |

SPECIFICATIONS

Reference Information

Packaging: Embossed Tape on Reel

UL File No.: Pending

CSA File No.: Pending

Mates With: Respective camera module

Designed In: mm

Electrical

Voltage: 50V

Current: 0.5A

Contact Resistance: 60 milliohms max.

Dielectric Withstanding Voltage: 150V AC

Insulation Resistance: 400 Megohms min.

Mechanical

Unmating Force: 1.00N

Durability: 30 cycles

Physical

Housing: PA Polyamide (nylon), UL 94V-0

Contact: Copper Alloy

Plating:

Contact Area — 12 μ"Gold

Solder Tail Area — Gold

Underplating — Nickel

PCB Thickness:

Operating Temperature: -55°C to +85°C



MARKETS AND APPLICATIONS

[查询"47337-0001"供应商](#)

- **Mobile phones**



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ORDERING INFORMATION

Description	Order No.	Imager Dim. (mm)	PCB Mounting Type	Pitch (mm)	Circuits	Physical Size (L x W x H) in mm	Contact Type	Capacity (Mega Pixels)
Camera Socket	47578-0001	6 x 6	Top	0.65	20	8.20 x 8.20 x 4.00	Bottom	0.30 MP (VGA)
	47356-0020	6 x 6	Mid	0.65	20	7.90 x 7.90 x 2.90	Bottom	0.30 MP (VGA)
	47249-0001	8 x 8	Top	0.90	24	10.10 x 10.10 x 4.20	Side	1 - 2 MP (CMOS)
	47357-0001	8 x 8	Mid	0.90	24	10.18 x 10.18 x 3.35	Side	1 - 2 MP (CMOS)
	47337-0001	8.5 x 8.5	Top	0.90	24	10.60 x 10.60 x 4.20	Side	2.0 MP (CMOS)



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